

N- and P-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY							
	V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)			
N-Channel	30	0.015 at V _{GS} = 10 V	18	12.5			
	30	0.020 at V _{GS} = 4.5 V	14	12.5			
P-Channel	- 30	0.026 at V _{GS} = - 10 V	- 16	8			
		0.039 at V _{GS} = -4.5 V	- 12	0			

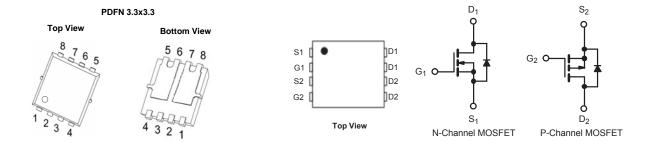
FEATURES

- DT-Trench Power MOSFET
- 100% R_g and UIS Tested



APPLICATIONS

- Networking DC-DC Power System
- Load Switch



ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted							
Parameter			N-Channel	P-Channel	Unit		
Drain-Source Voltage			30	- 30	V		
Gate-Source Voltage			± 20]		
	T _C = 25 °C		18	-16			
Continuous Prais Current (T. = 150 °C)	T _C = 70 °C	1 ,	15	-12			
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	- I _D	12 ^{b, c}	- 9.6 ^{b, c}			
	T _A = 70 °C]	9.4 ^{b, c}	- 7.3 ^{b, c}			
Pulsed Drain Current			72	-64	А		
Source-Drain Current Diode Current	T _C = 25 °C	1.	15	- 10			
	T _A = 25 °C	- I _S	8 ^{b, c}	- 5 ^{b, c}			
Pulsed Source-Drain Current		I _{SM}	72	-48			
Single Pulse Avalanche Current	1 = 0.4 mH		40	-32			
Single Pulse Avalanche Energy	L = 0 1 mH	E _{AS}	20	-17	mJ		
Maximum Power Dissipation	T _C = 25 °C		12.5	8			
	T _C = 70 °C		8	5.12	\Box w		
	T _A = 25 °C	P _D	4.3 ^{b, c}	2.0 ^{b, c}	VV		
	T _A = 70 °C	1	2.75 ^{b, c}	1.28 ^{b, c}	1		
Operating Junction and Storage Temperature Range			- 55 to	o 150	°C		

THERMAL RESISTANCE RATINGS								
			N-Ch	annel	P-Channel			
Parameter		Symbol	Тур.	Max.	Тур.	Max.	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	20	30	23	30	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	40	55	45	60	C/VV	

Notes:

- a. Based on T_C = 25 °C. b. Surface Mounted on 1" x 1" FR4 board.
- d. Maximum under Steady State conditions is 120 °C/W.



SPECIFICATIONS T _J = 25°				Min	т., а	Mess	Date	
Parameter Static	Symbol	Test Conditions		Min.	Typ. ^a	Max.	Unit	
	1	V _{GS} = 0 V, I _D = 250 μA N-Ch		30	1	<u> </u>		
Drain-Source Breakdown Voltage	V_{DS}	V _{GS} = 0 V, I _D = - 250 μA	P-Ch	- 30			V	
		I _D = 250 μA	N-Ch		44		mV/°C	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA	P-Ch		- 42			
		I _D = 250 μA	N-Ch		- 5.5			
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA	P-Ch		4.6			
		V _{DS} = V _{GS} , I _D = 250 μA	N-Ch	1		3	- V	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	P-Ch	- 1		- 3		
	1		N-Ch			100	<u> </u>	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	P-Ch			- 100	nA	
		V _{DS} = 24 V, V _{GS} = 0 V	N-Ch			1		
Zoro Coto Voltago Drain Current	1	V _{DS} = - 24 V, V _{GS} = 0 V	P-Ch			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 24 V, V _{GS} = 0 V, T _J = 55 °C	N-Ch			10	μA	
		V _{DS} = - 24 V, V _{GS} = 0 V, T _J = 55 °C	P-Ch			- 10	1	
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	N-Ch	22				
		V _{DS} = - 5 V, V _{GS} = - 10 V	P-Ch	- 20			A	
	R _{DS(on)}	V _{GS} = 10 V, I _D = 10 A	N-Ch		0.015	0.018		
		V _{GS} = - 10 V, I _D = - 8 A	P-Ch		0.026	0.035		
Drain-Source On-State Resistance ^b		V _{GS} = 4.5 V, I _D = 8 A	N-Ch		0.020	0.025	Ω	
		V _{GS} = - 4.5 V, I _D = - 5 A	P-Ch		0.039	0.050	1	
	9 _{fs}	V _{DS} = 15 V, I _D = 10 A	N-Ch		25			
Forward Transconductance ^b		V _{DS} = - 15 V, I _D = - 8 A	P-Ch		13		S	
Dynamic ^a					,			
Input Canacitanas	C _{iss}		N-Ch		1150			
Input Capacitance	Ciss	N-Channel $V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	P-Ch		1823		pF	
Output Capacitance	C _{oss}	V _{DS} - 24 V, V _{GS} - 0 V, I - I WIII2	N-Ch		260			
Output Capacitaries	Oss	P-Channel	P-Ch		375			
Reverse Transfer Capacitance	C _{rss}	V _{DS} = - 24 V, V _{GS} = 0 V, f = 1 MHz	N-Ch		110			
The verse manerer capacitance			P-Ch		135			
	Q _g	$V_{DS} = 24 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$	N-Ch		12.5	22		
Total Gate Charge		$V_{DS} = -24 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -8 \text{ A}$	P-Ch		8	20		
		N. Observat	N-Ch		5.3	9		
		N-Channel $V_{DS} = 24 \text{ V}, V_{GS} = 4.5 \text{ V} \text{ I}_{D} = 8 \text{ A}$	P-Ch		2.1	3.5	nC	
Gate-Source Charge		VDS - 24 V, VGS - 4.5 V ID - 0 A	N-Ch		1.4			
Cate-oduree Charge		P-Channel	P-Ch		0.58		_	
Gate-Drain Charge	Q _{gd}	$V_{DS} = -24 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -5 \text{ A}$	N-Ch		1.9			
Cato Brain Orlargo			P-Ch		1.3			
Gate Resistance	R_g	f = 1 MHz		0.5	2.0	4.5	Ω	
	· •g	1 171112	P-Ch	1.0	3.5	11	35	



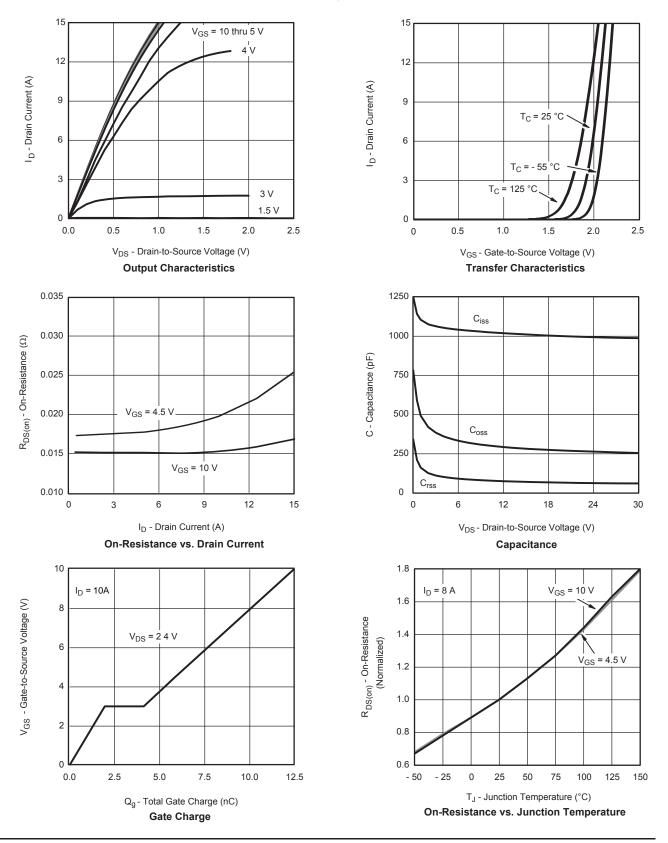
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Dynamic ^a							
Turn-On Delay Time	t _{d(on)}	N. Channel	N-Ch		7	14	
	*u(on)	N-Channel V_{DD} = 24 V, R_L = 4 Ω	P-Ch		9	16	- - -
Rise Time	t _r	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	N-Ch		10	25	
		g services	P-Ch		12	27	
Turn-Off Delay Time	t _{d(off)}	P-Channel	N-Ch		15	32	
	=(=::)	$V_{DD} = -24 \text{ V}, R_L = 4 \Omega$	P-Ch		31	65	
Fall Time	t _f	$I_D \cong -8 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$	N-Ch		9	22	ns
			P-Ch		10	23	
Turn-On Delay Time	$t_{d(on)}$	N-Channel	N-Ch		16	30	
· · · · · · · · · · · · · · · · · · ·	5(5.1)	$V_{DD} = 24 \text{ V}, R_L = 4 \Omega$	P-Ch		45	80	
Rise Time	t _r	$I_D \cong 8 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_q = 1 \Omega$	N-Ch		19	30	
		_	P-Ch		35	50	
Turn-Off Delay Time	t _{d(off)}	P-Channel	N-Ch P-Ch		16	30	
	, ,	$V_{DD} = -24 \text{ V}, R_L = 4 \Omega$	N-Ch		28 10	60 20	
Fall Time	t _f	$I_D \cong -5 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$			11	25	-
Drain-Source Body Diode Characterist	ics		P-Ch		11	25	
		I	N-Ch			18	
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C	P-Ch			-16	1
	I _{SM}		N-Ch			72	Α
Pulse Diode Forward Current ^a			P-Ch			-64	
	V _{SD}	I _S = 1.6 A			0.78	1.2	
Body Diode Voltage		I _S = - 1.6 A	P-Ch		- 0.75	- 1.2	V
Bud Birds Brown Brown Time	t _{rr}		N-Ch		7	34	
Body Diode Reverse Recovery Time			P-Ch		5	50	ns
Pody Diada Dayaraa Dasayary Chara-	Q _{rr}	N-Channel	N-Ch		4	25	50
Body Diode Reverse Recovery Charge		$I_F = 2 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$	P-Ch		1.3	35	nC
Poverse Posevery Fell Time	t _a	P-Channel	N-Ch		17		
Reverse Recovery Fall Time		$I_F = -2 \text{ A}$, dl/dt = -100 A/µs, $T_A = 25 \text{ °C}$	P-Ch		18		ne
Reverse Recovery Rise Time	t.		N-Ch		6		ns
neverse necovery rise Tille	t _b		P-Ch		14		

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

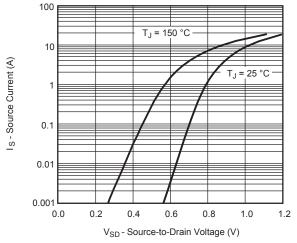
a. Guaranteed by design, not subject to production testing. b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.

N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

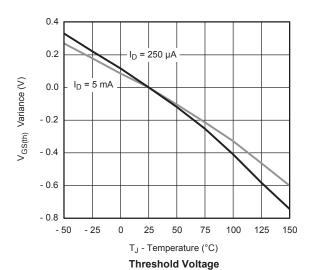




N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

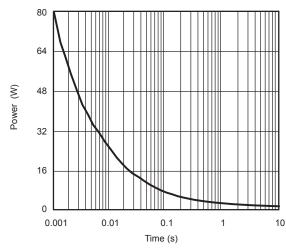


Source-Drain Diode Forward Voltage

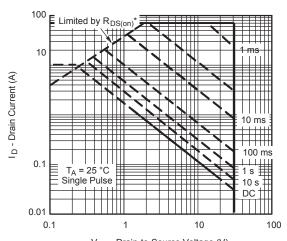


0.05 0.04 0.03 0.03 0.02 0.01 0 2 4 6 8 10

 $\label{eq:VGS} \mbox{V}_{GS} \mbox{ - Gate-to-Source Voltage (V)} \\ \mbox{On-Resistance vs. Gate-to-Source Voltage}$



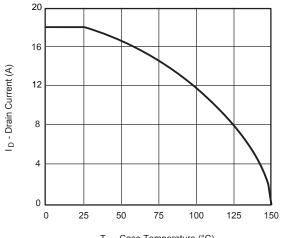
Single Pulse Power, Junction-to-Ambient



 $\rm V_{DS}$ - Drain-to-Source Voltage (V) * V $_{GS}$ > minimum V $_{GS}$ at which $\rm r_{DS(on)}$ is specified

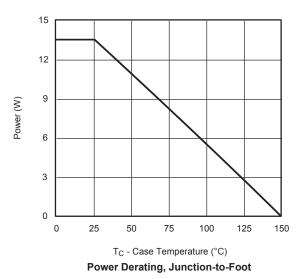
Safe Operating Area, Junction-to-Ambient

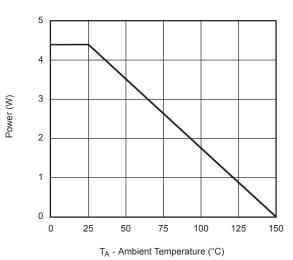
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



T_C - Case Temperature (°C)

Current Derating*

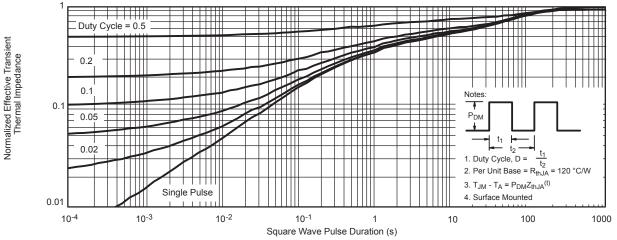




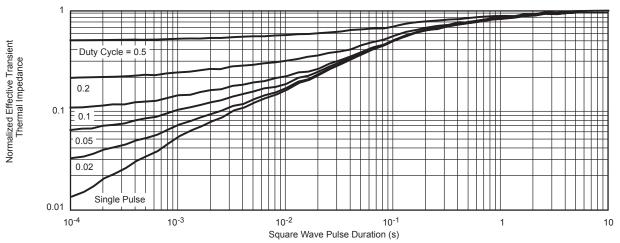
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



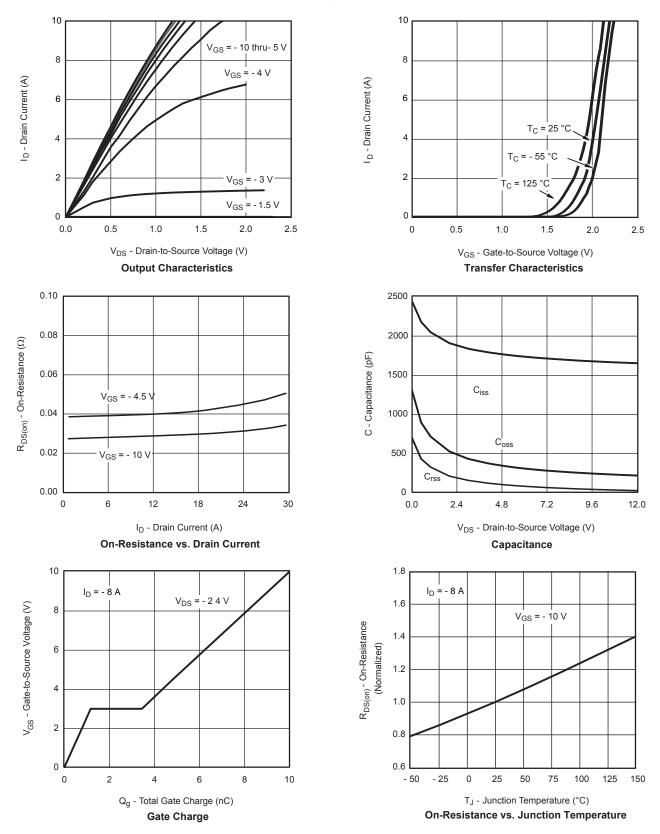
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

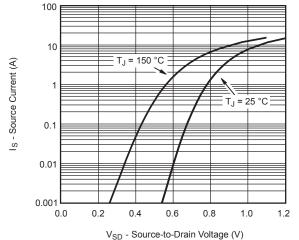


P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

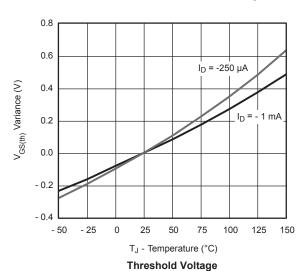




P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

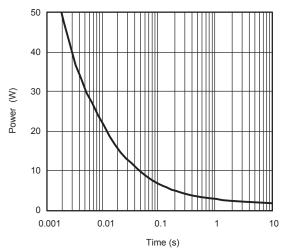


Source-Drain Diode Forward Voltage

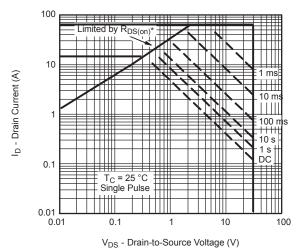


0.20 $I_D = -8 A$ 0.16 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ - On-Resistance (Ω) 0.12 0.08 $T_J = 125$ °C 0.04 $T_{J} = 25$ 0.00 2 0 1 3 5 6 9 10

 $\label{eq:VGS} V_{GS} \mbox{ - Gate-to-Source Voltage (V)} \\$ On-Resistance vs. Gate-to-Source Voltage



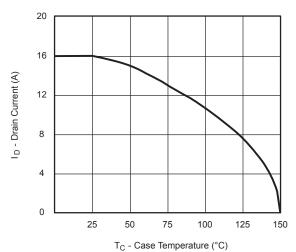
Single Pulse Power, Junction-to-Ambient



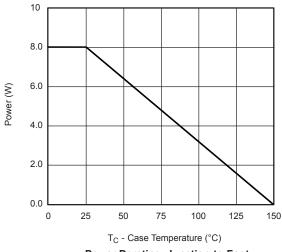
* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

Safe Operating Area, Junction-to-Ambient

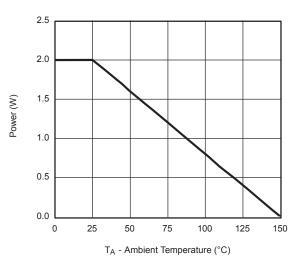
P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*



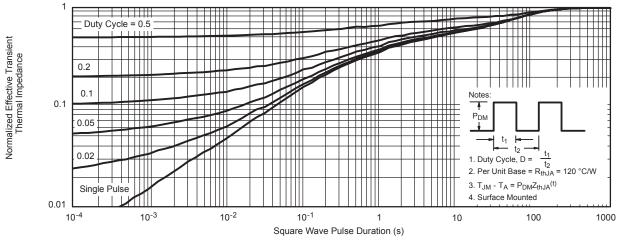




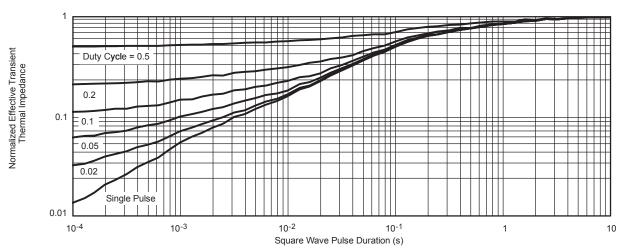
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

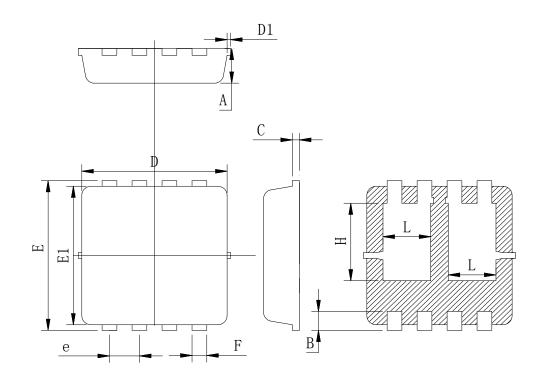


Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

PDFN 3.3X3.3-D PACKAGE OUTLINE



COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

Symbol	Min	Тур	Max
A	0.680	0.775	0.920
В	0.25	0.38	0.55
С	0.08	0.15	0.25
D	2.95	3.10	3.25
D1			0.12
Е	3.20	3.30	3.40
E1	2.85	3.00	3.15
e	0.50	0.65	0.80
F	0.23	0.32	0.41
Н	1.53	1.73	1.93
L	0.83	1.03	1.23





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